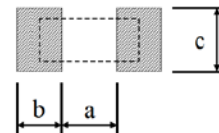
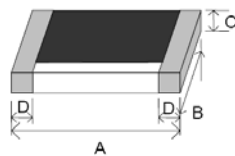


A. Electrical Specifications:

| Part No. | L (nH) | Tolerance | Q Min. | SRF Min. (GHz) | DCR Max. (Ω) | I DC Max. (mA) |
|------------|--------|-----------|----------|----------------|--------------|----------------|
| 0201TF-N10 | 0.1 | B, C, S | 8/500MHz | 9 | 0.20 | 400 |
| 0201TF-N20 | 0.2 | B, C, S | 8/500MHz | 9 | 0.20 | 400 |
| 0201TF-N30 | 0.3 | B, C, S | 8/500MHz | 9 | 0.20 | 400 |
| 0201TF-N40 | 0.4 | B, C, S | 8/500MHz | 9 | 0.25 | 350 |
| 0201TF-N50 | 0.5 | B, C, S | 8/500MHz | 9 | 0.25 | 350 |
| 0201TF-N60 | 0.6 | B, C, S | 8/500MHz | 9 | 0.25 | 350 |
| 0201TF-N70 | 0.7 | B, C, S | 8/500MHz | 9 | 0.30 | 300 |
| 0201TF-N80 | 0.8 | B, C, S | 8/500MHz | 9 | 0.30 | 300 |
| 0201TF-N90 | 0.9 | B, C, S | 8/500MHz | 9 | 0.30 | 300 |
| 0201TF-1N0 | 1.0 | B, C, S | 8/500MHz | 9 | 0.30 | 300 |
| 0201TF-1N1 | 1.1 | B, C, S | 8/500MHz | 9 | 0.35 | 300 |
| 0201TF-1N2 | 1.2 | B, C, S | 8/500MHz | 9 | 0.35 | 300 |
| 0201TF-1N3 | 1.3 | B, C, S | 8/500MHz | 9 | 0.45 | 250 |
| 0201TF-1N4 | 1.4 | B, C, S | 8/500MHz | 9 | 0.45 | 250 |
| 0201TF-1N5 | 1.5 | B, C, S | 8/500MHz | 9 | 0.45 | 250 |
| 0201TF-1N6 | 1.6 | B, C, S | 8/500MHz | 9 | 0.55 | 200 |
| 0201TF-1N7 | 1.7 | B, C, S | 8/500MHz | 9 | 0.55 | 200 |
| 0201TF-1N8 | 1.8 | B, C, S | 8/500MHz | 9 | 0.55 | 200 |
| 0201TF-1N9 | 1.9 | B, C, S | 8/500MHz | 9 | 0.55 | 200 |
| 0201TF-2N0 | 2.0 | B, C, S | 8/500MHz | 8 | 0.70 | 200 |
| 0201TF-2N1 | 2.1 | B, C, S | 8/500MHz | 8 | 0.70 | 200 |
| 0201TF-2N2 | 2.2 | B, C, S | 8/500MHz | 8 | 0.70 | 200 |
| 0201TF-2N3 | 2.3 | B, C, S | 8/500MHz | 8 | 0.80 | 150 |
| 0201TF-2N4 | 2.4 | B, C, S | 8/500MHz | 8 | 0.80 | 150 |
| 0201TF-2N5 | 2.5 | B, C, S | 8/500MHz | 8 | 0.80 | 150 |
| 0201TF-2N6 | 2.6 | B, C, S | 8/500MHz | 8 | 0.80 | 150 |
| 0201TF-2N7 | 2.7 | B, C, S | 8/500MHz | 8 | 0.80 | 150 |
| 0201TF-2N8 | 2.8 | B, C, S | 8/500MHz | 6 | 1.00 | 150 |
| 0201TF-2N9 | 2.9 | B, C, S | 8/500MHz | 6 | 1.00 | 150 |
| 0201TF-3N0 | 3.0 | B, C, S | 8/500MHz | 6 | 1.00 | 150 |
| 0201TF-3N1 | 3.1 | B, C, S | 8/500MHz | 6 | 1.00 | 150 |
| 0201TF-3N2 | 3.2 | B, C, S | 8/500MHz | 6 | 1.00 | 150 |
| 0201TF-3N3 | 3.3 | B, C, S | 8/500MHz | 6 | 1.00 | 150 |
| 0201TF-3N4 | 3.4 | B, C, S | 8/500MHz | 6 | 1.20 | 150 |
| 0201TF-3N5 | 3.5 | B, C, S | 8/500MHz | 6 | 1.20 | 150 |
| 0201TF-3N6 | 3.6 | B, C, S | 8/500MHz | 6 | 1.20 | 150 |
| 0201TF-3N7 | 3.7 | B, C, S | 8/500MHz | 6 | 1.20 | 150 |
| 0201TF-3N8 | 3.8 | B, C, S | 8/500MHz | 6 | 1.20 | 150 |
| 0201TF-3N9 | 3.9 | B, C, S | 8/500MHz | 6 | 1.20 | 150 |
| 0201TF-4N0 | 4.0 | B, C, S | 8/500MHz | 6 | 1.20 | 150 |
| 0201TF-4N4 | 4.4 | B, C, S | 8/500MHz | 6 | 1.30 | 140 |
| 0201TF-4N7 | 4.7 | B, C, S | 8/500MHz | 6 | 1.40 | 130 |
| 0201TF-4N9 | 4.9 | B, C, S | 8/500MHz | 6 | 1.60 | 130 |
| 0201TF-5N6 | 5.6 | G, J | 8/500MHz | 4 | 1.80 | 130 |
| 0201TF-6N1 | 6.1 | G, J | 8/500MHz | 4 | 2.00 | 120 |
| 0201TF-6N8 | 6.8 | G, J | 8/500MHz | 4 | 2.30 | 110 |
| 0201TF-7N4 | 7.4 | G, J | 8/500MHz | 4 | 2.80 | 110 |
| 0201TF-8N2 | 8.2 | G, J | 8/500MHz | 3 | 3.00 | 110 |
| 0201TF-9N1 | 9.1 | G, J | 8/500MHz | 3 | 3.25 | 100 |
| 0201TF-9N2 | 9.2 | G, J | 8/500MHz | 3 | 3.25 | 100 |
| 0201TF-10N | 10.0 | G, J | 8/500MHz | 2 | 3.50 | 80 |

B. Dimensions and Recommend Land Pattern: (mm/Inch)

| Series | A | B | C | D | a | b | c |
|--------|----------------------------|----------------------------|----------------------------|----------------------------|------------------|-----------------|-----------------------------|
| 0201TF | 0.60±0.05 (0.024±0.002) | 0.30±0.05 (0.012±0.002) | 0.23±0.05 (0.009±0.002) | 0.15±0.05 (0.006±0.002) | 0.30 (0.0118) | 0.25 (0.010) | 0.30±0.20 (0.0118±0.008) |



Recommend Land Pattern

C. Part Number (Example):



D. General information:

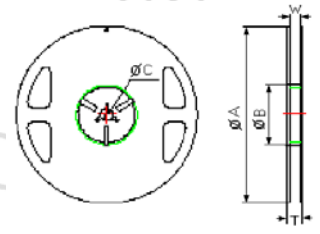
1. 0201TF-xxx, “0201TF” = P/N, “xxx” = Inductance, “_” = Tolerance.
2. Tolerance “_”: J: ± 5%, H: ± 3%, G: ± 2%, F: ± 1%, B: ± 0.1nH, C: ± 0.2nH, S: ±0.3nH.
3. A Photo Lithographic Single Layer Ceramic Chip.
4. High SRF, Excellent Q, Superior Temperature Stability
5. Tight Tolerance of ± 1% or ± 0.1nH
6. Stable Inductance in High Frequency Circuit
7. Maximum Temperature Rise: 15°C (when measured at 25°C ambient).
8. Inductance & Q measured using the HP4286A and Agilent 16196B.
9. SRF measured using the HP8720D or HP8753E.
10. DCR measured using the 502BC.
11. Operating temperature: -40°C to +125°C.
12. Storage Temperature: 25°C ± 3°C; Humidity < 80% RH
13. Inductance Range: 0.10 nH (400 mA) ~ 10.0 nH (80 mA), SRF from 9.0 GHz to 2.0 GHz.
14. MSL: Level 1.

E. Applications:

1. Cellular-phone, Pagers and GPS Products.
2. VCO, TCXO Circuit and RF Transceiver Module.
3. Wireless LAN, Bluetooth Module, Communication Appliances Hybrid.

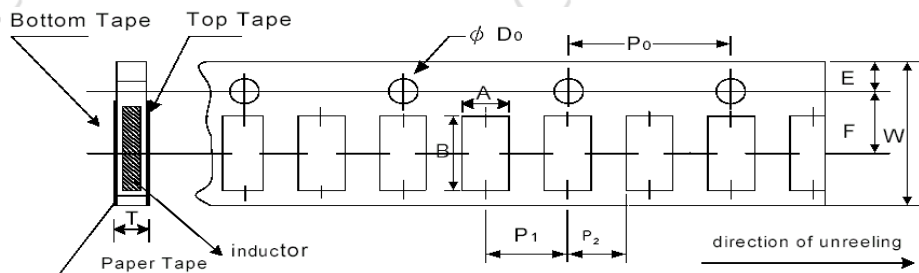
F. Reel Specification:

| Series | φA | φB | φC | W | T | Quantity |
|--------|--------------------|-------------------------|----------------------------|--------------------------|---------------------------|------------|
| 0201TF | 178±1 (7±0.040) | 60±1.0 (0.236±0.040) | 13.5±0.70 (0.531±0.028) | 9.5±1.0 (0.374±0.040) | 11.5±1.0 (0.453±0.040) | 10,000 PCS |



G. Paper Tape Specification:

| Series | A | B | W | E | F | Po | P1 | P2 | φDo | T |
|--------|----------------------------|----------------------------|----------------------------|----------------------------|----------------------------|----------------------------|----------------------------|----------------------------|----------------------------|-----------------------------|
| 0201TF | 0.40±0.05 (0.016±0.002) | 0.70±0.05 (0.028±0.002) | 8.00±0.10 (0.315±0.004) | 1.75±0.05 (0.069±0.002) | 3.50±0.05 (0.138±0.002) | 4.00±0.10 (0.158±0.004) | 2.00±0.05 (0.079±0.002) | 2.00±0.05 (0.079±0.002) | 1.55±0.05 (0.061±0.002) | 0.42±0.02 (0.017±0.0008) |



Tape & Reel Storage Temperature: 25°C ± 3°C, Humidity: < 80% RH.

H. Environmental Characteristics:

| ITEM | Specification | Test Method |
|--------------------------------|----------------------|--|
| 1 Inductance | As SPEC. | Measuring equipment and fixture: HP4287 + Agilent 16196C |
| 2 Insulation Resistance | >1000MΩ | MIL-STD-202F Method 302 Apply 100V _{ac} for 1 minute |
| 3 Damp Heat with Load | $\Delta L \leq 10\%$ | MIL-STD-202F Method 103B 40±2°C, 90~95% R.H. Max. working voltage for 1000 hrs with 1.5 hrs "ON" and 0.5 hrs "OFF" |
| 4 Bending Strength | As SPEC. | JIS-C-5201-1 6.1.4 Bending Amplitude 3mm for 10 seconds |
| 5 Solder-ability | 95% min coverage | MIL-STD-202F Method 208H 245±5°C for 3 seconds |
| 6 Resistance to Soldering Heat | $\Delta L \leq 10\%$ | MIL-STD-202F Method 210E 260±5°C for 10 seconds |
| 7 Dielectric Withstand Voltage | >100V | MIL-STD-202F Method 301. Apply 100VA (rms) for 1minute. |
| 8 High Temperature Exposure | $\Delta L \leq 10\%$ | JIS-C-5201-1-7.2 85°C ± 2°C, 1000 +48/-0 hours |
| 9 Low Temperature Storage | $\Delta L \leq 10\%$ | JIS-C-5201-1-7.1 -40°C ± 3°C, 1000 +48/-0 hours |
| 10 Temperature Cycle | $\Delta L \leq 10\%$ | JIS-C-5201-1-7.4 -40/RT/85/RT, 10 cycles |

- Storage Temperature: 25±3°C; Humidity < 80% RH

J. Solder Profile:

